

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 183 | (semiconductor or die or chip or IC) same (guard\$3 or protect\$3) with scrib\$3 | USPAT | OR | ON | 2005/09/14 13:17 |
| L2 | 183 | (semiconductor or die or chip or IC) same (guard\$3 or protect\$3) with scrib\$3 | USPAT | OR | ON | 2005/09/14 13:20 |
| L3 | 73 | (semiconductor or die or chip or IC) same (guard\$3 or protect\$3) with scrib\$3 near (ring or line) | USPAT | OR | ON | 2005/09/14 14:21 |
| L4 | 21 | (semiconductor or die or chip or IC) and (guard\$3 or protect\$3) near (line or ring) with scrib\$3 near (ring or line) | USPAT | OR | ON | 2005/09/14 14:17 |
| L5 | 1 | (semiconductor or die or chip or IC) and scrib\$3 near (ring or line) with function with (guard\$3 or protect\$3) | USPAT | OR | ON | 2005/09/14 14:19 |
| L6 | 3 | (semiconductor or die or chip or IC) and scrib\$3 near (ring or line) with work\$3 with (guard\$3 or protect\$3) | USPAT | OR | ON | 2005/09/14 14:21 |
| L7 | 125 | (semiconductor or die or chip or IC) and scrib\$3 near (ring or line) with (guard\$3 or protect\$3) | USPAT | OR | ON | 2005/09/14 15:16 |
| L8 | 104 | 7 not 4 | USPAT | OR | ON | 2005/09/14 14:22 |
| L9 | 64 | scrib\$3 near (ring or line) with (guard\$3 or protect\$3) with (semiconductor or die or chip or IC) | USPAT | OR | ON | 2005/09/14 15:16 |
| L10 | 1 | "5721151".PN. | USPAT; USOCR | OR | OFF | 2005/09/14 15:28 |
| L21 | 774 | 257/620 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:37 |
| L22 | 661 | 257/620 | USPAT | OR | ON | 2005/09/14 16:38 |
| L23 | 113 | 21 not L22 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:39 |

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|-----|-------|--|---|----|-----|------------------|
| L24 | 661 | 21 not 23 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:39 |
| L25 | 102 | 257/483 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:47 |
| L26 | 162 | 257/484 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:54 |
| L27 | 5073 | 257/758 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:54 |
| S1 | 19 | "6399897" or "6165886" or "4914503" | USPAT | OR | OFF | 2005/03/17 19:08 |
| S2 | 11 | "6362524" or "5583380" or "6212077" or "006545348" | USPAT | OR | OFF | 2005/03/17 19:11 |
| S3 | 34 | "6300223" or "5831330" or "5834829" or "6028347" | USPAT | OR | OFF | 2005/03/17 19:11 |
| S4 | 37 | "6300223" or "5831330" or "5834829" or "6028347" or "20010030358" | US-PGPUB; USPAT | OR | OFF | 2005/03/17 19:18 |
| S5 | 9 | "5717245".pn. or "6028497".pn. or "5864092".pn. or "6105226". pn. or "5998245".pn. or "6028347".pn. or "5185654".pn. or "4868716".pn. or "6180876". pn. | US-PGPUB; USPAT | OR | OFF | 2005/03/17 19:19 |
| S6 | 17 | "5831330" | USPAT | OR | OFF | 2005/03/18 14:21 |
| S7 | 23386 | (semiconductor or die or chip or IC) with seal\$3 | USPAT | OR | ON | 2005/03/18 14:22 |
| S8 | 1656 | (semiconductor or die or chip or IC) with seal\$3 with ring | USPAT | OR | ON | 2005/03/18 14:59 |
| S9 | 675 | 257/620 | USPAT | OR | ON | 2005/09/14 16:37 |
| S10 | 79 | (semiconductor or die or chip or IC) with dummy with ring | USPAT | OR | ON | 2005/03/18 16:22 |
| S11 | 1 | "5024970".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:00 |

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| S12 | 1 | "5414297".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:00 |
| S13 | 1 | "5530280".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:00 |
| S14 | 1 | "5559362".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:00 |
| S15 | 1 | "5665655".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:01 |
| S16 | 1 | "5698892".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:01 |
| S17 | 1 | "5772906".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:01 |
| S18 | 1 | "5831330".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:01 |
| S19 | 1 | "5891808".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:03 |
| S20 | 1 | "5772906".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:04 |
| S21 | 1 | "5723385".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:08 |
| S22 | 1 | "4835592".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:16 |
| S23 | 1 | "5239191".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:16 |
| S24 | 1 | "5285082".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:16 |
| S25 | 1 | "6121677".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:16 |
| S26 | 1 | "6174789".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:17 |
| S27 | 1 | "6194739".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:17 |
| S28 | 1337 | (semiconductor or die or chip or IC) with (guard\$3 or protect\$3 or scribe\$3) with ring | USPAT | OR | ON | 2005/03/18 16:22 |
| S29 | 1924 | (semiconductor or die or chip or IC) with (guard\$3 or protect\$3 or scribe\$3 or cutt\$3) with ring | USPAT | OR | ON | 2005/03/18 17:20 |
| S30 | 1 | "5818111".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |
| S31 | 1 | "5834829".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |
| S32 | 1 | "6190947".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |
| S33 | 1 | "6207554".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |

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| S34 | 1 | "6271102".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |
| S35 | 1 | "6271102".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |
| S36 | 1 | "6291317".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:37 |
| S37 | 1 | "6294439".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:38 |
| S38 | 1 | "6534386".PN. | USPAT; USOCR | OR | OFF | 2005/03/18 16:38 |
| S39 | 126 | 257/483 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/14 16:46 |
| S40 | 227 | 257/484 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 17:23 |
| S41 | 25749 | coefficient near thermal near expansion | USPAT | OR | OFF | 2005/03/21 12:13 |
| S42 | 0 | coefficient near thermal near expansion with "/K" | USPAT | OR | OFF | 2005/03/21 12:14 |
| S43 | 7 | coefficient near thermal near expansion with degree near "K" | USPAT | OR | OFF | 2005/03/21 12:16 |
| S44 | 0 | coefficient near thermal near expansion with degree near "K" with ("Si" or silicon or silicone) | USPAT | OR | OFF | 2005/03/21 12:17 |
| S45 | 2 | coefficient near thermal near expansion with degree near "K" same ("Si" or silicon or silicone) | USPAT | OR | OFF | 2005/03/21 12:17 |
| S46 | 3054 | coefficient near thermal near expansion with ("Si" or silicon or silicone) | USPAT | OR | OFF | 2005/03/21 12:18 |
| S47 | 50 | coefficient near thermal near expansion with ("Si" or silicon or silicone) with "K" | USPAT | OR | OFF | 2005/03/21 12:53 |
| S48 | 18 | (semiconductor or die or chip or IC) with (guard\$3 or protect\$3 or scrib\$3 or cutt\$3) with ring and corner with (wider or bigger or wide or big or large) | USPAT | OR | OFF | 2005/03/24 12:04 |

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| S49 | 7 | (semiconductor or die or chip or IC) with (guard\$3 or protect\$3 or scribe\$3 or cutt\$3) with ring same corner with (wider or bigger or wide or big or large) | USPAT | OR | OFF | 2005/03/24 12:09 |
| S50 | 2 | (semiconductor or die or chip or IC) with (guard\$3 or protect\$3 or scribe\$3 or cutt\$3) with ring same corner with (wider or bigger or wide or big or large) | US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/14 13:16 |
| S51 | 4854 | 257/758 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/24 20:50 |